



# International Test Conference (India)

*Building on the Test EcoSystem to enable and support electronics growth in ASIA*

**July 10-12, 2017, Bangalore, India**

## Call for papers

International Test Conference is the world's premier venue dedicated to the electronic test of devices, boards and systems—covering the complete cycle from design verification, design-for-test, design-for-manufacturing, silicon debug, manufacturing test, system test, diagnosis, reliability and failure analysis, and back to process and design improvement. At ITC, design, test, and yield professionals can confront challenges faced by the industry, and learn how these challenges are being addressed by the combined efforts of academia, design tool and equipment suppliers, designers, and test engineers. This ITC conference will be focusing on Test technology development in Asia and India but the submissions may not be limited to topics related to this region. Topics related to DFT and test development across multi geographical regions will be of special interest.

This conference is being held in India under the International Test conference banner to invite researchers, industry teams to present their development work which has a focus on ASIA. This includes design teams which have multiple national presences and are developing designs and products across multiple sites across the world.

Authors are invited to submit original, unpublished papers describing recent work in the field of test and design. In addition, authors are invited to submit high quality, practical, industry best practices. Submissions simultaneously under review or accepted by another conference, symposium or journal, will be summarily rejected.

### Submissions must include:

- Title of paper.
- Name, affiliation, e-mail address of each author.
- The corresponding author(s). ITC will communicate with the corresponding author(s).
- One or two topic(s) from the topic list, or a description of your topic.
- An electronic copy of a complete paper up to **10 pages**, or an extended summary up to 6 pages. **Submissions less than 4 pages are rarely accepted.**
- An abstract of 500 words or less to be entered online.

**Paper submission deadline: Mar 31, 2017**

**Author notification: May 19, 2017**

**Final manuscript due: June 16, 2017**

Authors are also invited to submit a single-page poster proposal. Posters are a useful way of presenting late-breaking results, getting feedback on an innovative method, or participating without having to write a full paper. Acceptance as a poster does not preclude submission of a more complete work as an ITC paper in 2017. Poster proposal abstracts should be no longer than a single page.

**Poster submission deadline: April 21, 2017**

**Author notification: June 2, 2017**

**Final manuscript due: June 16, 2017**

For detailed information about the submission process, requirements and deadlines, the selection process and any other questions regarding the program itself or contact information, please consult the ITC web site at <http://www.itctestweekindia.org> or email the program chair [navin.bishnoi@globalfoundries.com](mailto:navin.bishnoi@globalfoundries.com)

*ITC India invites submissions on the latest advances in test, validation and diagnosis of ICs, boards and systems*

### Topics of interest include (not limited to):

3D/2.5D Test  
 Adaptive Test in Practice  
 ATE/Probe Card Design  
 Advances in Boundary Scan  
 Bring Up  
 Data Driven Methods  
 Data Exchange and Infrastructure  
 Defect-Oriented Testing  
 DFM and Test Diagnosis  
 Economics of Test  
 End-to-End Data Analysis  
 Embedded BIST & DFT  
 Emerging Defect Mechanisms  
 Hardware Security and Trust  
 IoT Testing  
 Jitter, High-Speed I/O and RF Test  
 Known-Good-Die testing  
 Memory Test and Repair  
 MEMS Testing  
 Mixed-Signal and Analog Test  
 New Technologies and Test  
 On-Chip Test Compression  
 Online Test  
 Pre- and Post- Silicon Validation  
 Power Issues in Test  
 Protocol-aware Test  
 Reliability and Resilience  
 Scan Based Test  
 SoC/SiP/NoC Test  
 Silicon Debug  
 Simulation and Test  
 System Test (Applications)  
 System Test (Hardware/Software)  
 Test-to-Design Feedback  
 Test Escape Analysis  
 Test Flow Optimizations  
 Test Generation and Validation  
 Test Resource Partitioning  
 Test Standards  
 Test Time Analysis and Reduction  
 Testing High Speed Optics/Photonics  
 Timing Test  
 Yield Analysis and Optimization